Abstract

A research is carried to evaluate the performance between the pulse plating and pulse reverse plating technique. In both the technique employed the composition of the bath is kept constant. Both the plating is done on a double sided Printed Circuit Board for the connection between the two layers. The metal used for plating is silver rather than the conventional copper. The evaluation of parameters such as hardness and current efficiency is carried out.

References

Investigations on the Characteristics of Pulse Plating on Printed Circuit Board


**Index Terms**

Computer Science

Circuits And Systems

**Keywords**

Printed Circuit Board    Pulse plating    Pulse Reverse plating    silver    current efficiency